SPECIFICATIONS

Customer	
Product Name	**Multi-layer Chip Ferrite Bead**
Sunlord Part Number	**MZAH Series**
Customer Part Number	

[☒New Released, ☐Revised] **SPEC No.: MZAH0301230000**

【This SPEC is total 10 pages including specifications and appendix.】

【ROHS Compliant Parts】

Approved By	Checked By	Issued By

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【For Customer approval Only】 Date:_____

Qualification Status: ☐ Full ☐ Restricted ☐ Rejected

Approved By	Verified By	Re-checked By	Checked By

Comments:

_____

【Version change history】

Rev.	Effective Date	Changed Contents	Change reasons	Approved By
01	/	New release	/	Hai Guo

1. Scope

This specification applies to MZAH series of multi-layer ferrite chip bead.

2. Product Description and Identification (Part Number)

1) Description:

MZAH series of Multi-layer ferrite chip beads.

2) Product Identification (Part Number)

MZAH	1005	F	152	-R40	T	F	□□□
①	②	③	④	⑤	⑥	⑦	⑧

① Type	
MZAH	Audio filter for high frequency noise

② External Dimensions (L X W) (mm)	
1005 [0402]	1.0 X 0.5
1608 [0603]	1.6 X 0.8

③ Material Code
F,G,L

④ Nominal Impedance	
Example	Nominal Value
600	60Ω
471	470Ω
152	1500Ω

⑤ Rate Current	
R40	0.40A
1R5	1.5A

⑥ Packing	
T	Tape Carrier Package

⑦ HSF Products
Hazardous Substance Free Products

⑧ Design Code	
□□□	Design Code (* Standard product is blank)

3. Electrical Characteristics

Please refer to **Appendix A** (Page 9).

1) Operating and storage temperature range (individual chip without packing): -40℃ ~+85℃.
2) Storage temperature range (packaging conditions): -10℃~+40℃ and RH 70% (Max.).

4. Shape and Dimensions

1) Dimensions and recommended PCB pattern for reflow soldering: See **Fig.4-1**, **Fig.4-2** and **Table 4-1**.
2) Structure: See **Fig. 4-3** and **Fig. 4-4**.

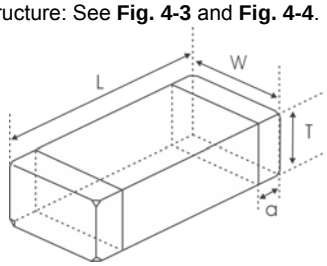


Fig. 4-1

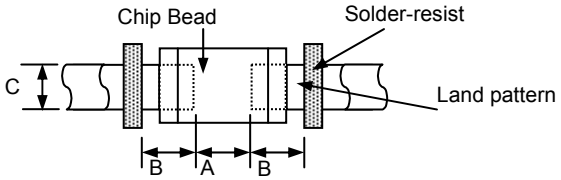


Fig. 4-2

Type	L	W	T	a	A	B	C
1005 [0402]	1.0±0.15 [0.039±0.006]	0.5±0.15 [0.020±0.006]	0.5±0.15 [0.020±0.006]	0.25±0.1 [0.010±0.004]	0.45~0.55	0.40~0.50	0.45~0.55
1608 [0603]	1.60±0.15 [0.063±0.006]	0.8±0.15 [0.031±0.006]	0.8±0.15 [0.031±0.006]	0.3±0.2 [0.012±0.008]	0.60~0.80	0.60~0.80	0.60~0.80

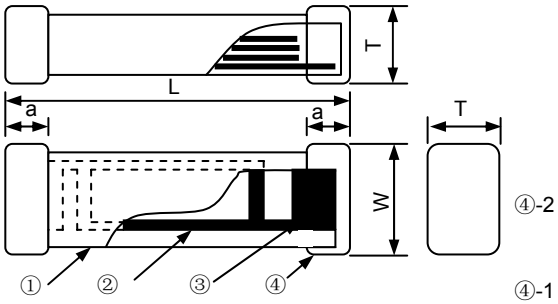


Fig. 4-3

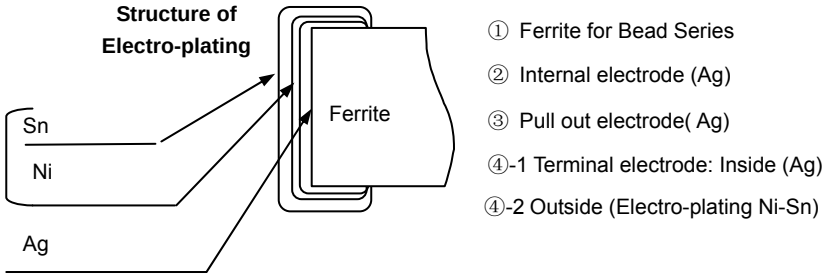


Fig. 4-4

3) Material information: See **Table 4-2**.

[Table 4-2]

Code	Part Name	Material Name
①	Ferrite Body	Ferrite Powder
②	Inner Coils	Silver Paste
③	Pull-out Electrode (Ag)	Silver Paste
④-1	Terminal Electrode: Inside Ag	Termination Silver Composition
④-2	Electro-Plating: Ni/Sn plating	Plating Chemicals

5. Test and Measurement Procedures

5.1 Test Conditions

Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

a. Ambient Temperature: 20±15℃
b. Relative Humidity: 65±20%
c. Air Pressure: 86kPa to 106kPa

If any doubt on the results, measurements/tests should be made within the following limits:

a. Ambient Temperature: 20±2℃
b. Relative Humidity: 65±5%
c. Air Pressure: 86kPa to 106kPa

5.2 Visual Examination

a. Inspection Equipment: 20× magnifier

5.3 Electrical Test

5.3.1 DC Resistance (DCR)

a. Refer to **Appendix A**.
b. Test equipment (Analyzer): High Accuracy Milliohmmeter-HP4338B or equivalent.

5.3.2 Impedance (Z)

a. Refer to **Appendix A**.
b. Test equipment: High Accuracy RF Impedance /Material Analyzer-E4991A or equivalent.
Test fixture: HP16192A
Test signal: -20dBm or 50mV
c. Test frequency refers to **Appendix A**.

5.3.3 Rated Current

a. Refer to **Appendix A**.
b. Test equipment (see **Fig. 5.3.3-1**): Electric Power, Electric current meter, Thermometer.
c. Measurement method (see **Fig. 5.3.3-1**):
1. Set test current to be 0mA.
2. Measure initial temperature of chip surface.
3. Gradually increase voltage and measure chip temperature for corresponding current.
d. Definition of Rated Current (Ir): Ir is direct electric current as chip surface temperature rose just40℃ against chip initial surface temperature(Ta) (see **Fig. 5.3.3-2**).

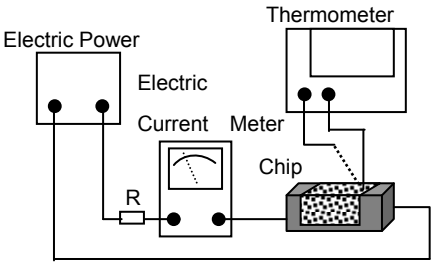


Fig. 5.3.3-1

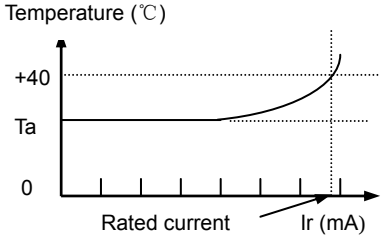
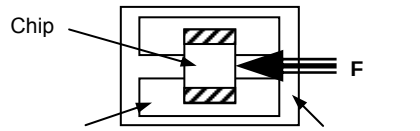
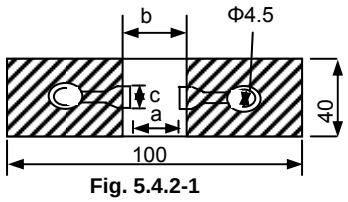
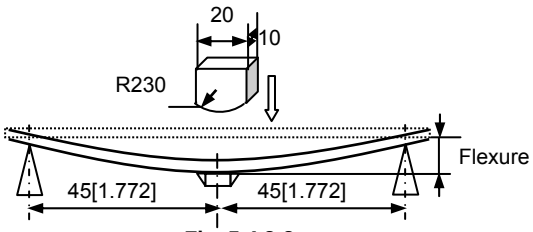
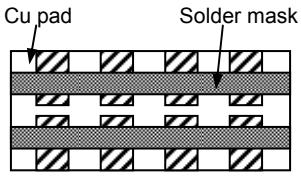
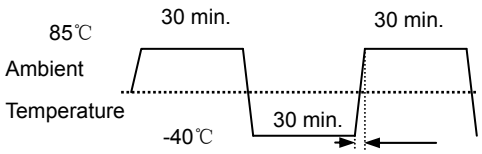


Fig. 5.3.3-2

5.4 Reliability Test

Items	Requirements	Test Methods and Remarks
5.4.1 Terminal Strength	No removal or split of the termination or other defects shall occur.  **Fig.5.4.1-1**	① Solder the bead to the testing jig (glass epoxy board shown in **Fig. 5.4.1-1**) using leadfree solder. Then apply a force in the direction of the arrow. ② 5N force for 1005 and 1608 series ③ Keep time: 10±1s ④ Speed: 1.0mm/s
5.4.2 Resistance to Flexure	No visible mechanical damage. Unit: mm [inch] Type / a / b / c 1005[0402] / 0.4 / 1.5 / 0.5 1608[0603] / 1.0 / 3.0 / 1.2  **Fig. 5.4.2-1**	① Solder the bead to the test jig (glass epoxy board shown in **Fig. 5.4.2-1**) Using a leadfree solder. Then apply a force in the direction shown **Fig. 5.4.2-2.** ② Flexure: 2mm ③ Pressurizing Speed: 0.5mm/sec. ④ Keep time: 30 sec.  **Fig. 5.4.2-2**
5.4.3 Vibration	① No visible mechanical damage. ② Impedance change: within ±20%  **Fig. 5.4.3-1**	① Solder the bead to the testing jig (glass epoxy board shown in **Fig. 6.4.3-1**) using leadfree solder. ② The bead shall be subjected to a simple harmonic motion having total amplitude of 1.5 mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ The frequency range from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in each 3mutually perpendicular directions (total of 6 hours).
5.4.4 Dropping	① No visible mechanical damage. ② Impedance change: within ±20%	Drop chip bead 10 times on a concrete floor from a height of 100 cm.
5.4.5 Temperature	Impedance change should be within ±20% of initial value measuring at 20℃.	Temperature range: -40℃ ~ 85℃. Reference temperature: +20℃.
5.4.6 Solderability	① No visible mechanical damage. ② Wetting shall exceed 75% coverage for 0603 series; exceed 95% for others	① Solder temperature: 240±2℃ ② Duration: 3 sec. ③ Solder: Sn/3.0Ag/0.5Cu. ④ Flux: 25% Resin and 75% ethanol in weight.
5.4.7 Resistance to Soldering Heat	① No visible mechanical damage. ② Wetting shall exceed 75% coverage for 0603 series; exceed 95% for others ③ Impedance change: within ±20%.	① Solder temperature: 260±3℃ ② Duration: 5 sec. ③ Solder: Sn/3.0Ag/0.5Cu. ④ Flux: 25% Resin and 75% ethanol in weight. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

5.4.8 Thermal Shock	① No mechanical damage. ② Impedance change: Within ±20%  **Fig. 5.4.8-1**	① Temperature, Time: (See **Fig.5.4.8-1**). -40℃ for 30±3 min→ 85℃ for 30±3min. ② Transforming interval: 20 sec. Max. ③ Tested cycle: 100 cycles. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5.4.9 Resistance to Low Temperature	① No visible mechanical damage. ② Impedance change: within ±20%.	① Temperature: -40±2℃ ② Duration: 1000^{+24} hours. ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5.4.10 Resistance to High Temperature	① No mechanical damage. ② Impedance change: within ±20%.	① Temperature: 85±2℃ ② Duration: 1000^{+24} hours. ③ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5.4.11 Damp Heat (Steady States)	① No visible mechanical damage. ② Impedance change: within ±20%.	① Temperature: 60±2℃. ② Humidity: 90% to 95% RH. ③ Duration: 1000^{+24} hours. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5.4.12 Loading Under Damp Heat	① No visible mechanical damage. ② Impedance change: within ±20%.	① Temperature: 60±2℃. ② Humidity: 90% to 95% RH. ③ Duration: 1000^{+24} hours. ④ Applied current: Rated current. ⑤ The chip shall be stabilized at normal condition for 1~2 hours before measuring.
5.4.13 Loading at High Temperature (Life Test)	① No visible mechanical damage. ② Impedance change: within ±20%.	① Temperature: 85±2℃ ② Duration: 1000^{+24} hours. ③ Applied current: Rated current. ④ The chip shall be stabilized at normal condition for 1~2 hours before measuring.

6. Packaging and Storage

6.1 Packaging

Tape Carrier Packaging:

Packaging code: T

a. Tape carrier packaging are specified in attached figure **Fig.6.1-1~3**

b. Tape carrier packaging quantity please see the following table:

Type	1005[0402]	1608[0603]
T(mm)	0.5±0.15	0.8±0.15
Tape	Paper Tape	Paper Tape
Quantity	10K	4K

(1) Taping Drawings (Unit: mm)

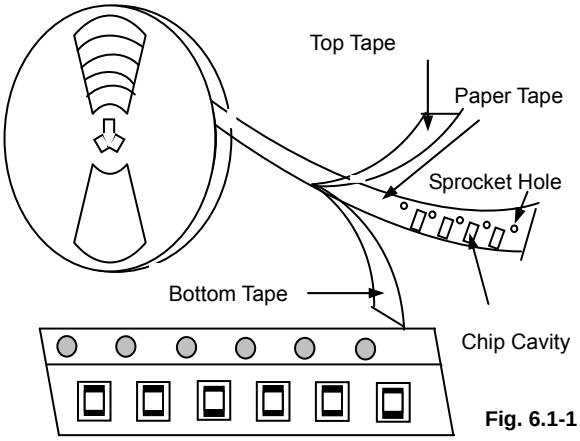


Fig. 6.1-1

Remark: The sprocket holes are to the right as the tape is pulled toward the user.

(2) Taping Dimensions (Unit: mm)

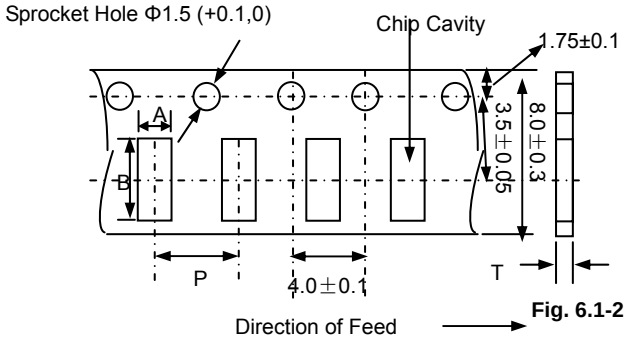


Fig. 6.1-2

Type	A	B	P	T max
1005[0402]	0.65±0.1	1.15±0.1	2.0±0.05	0.8
1608[0603]	1.0±0.2	1.8±0.2	4.0±0.1	1.1

(3) Reel Dimensions (Unit: mm)

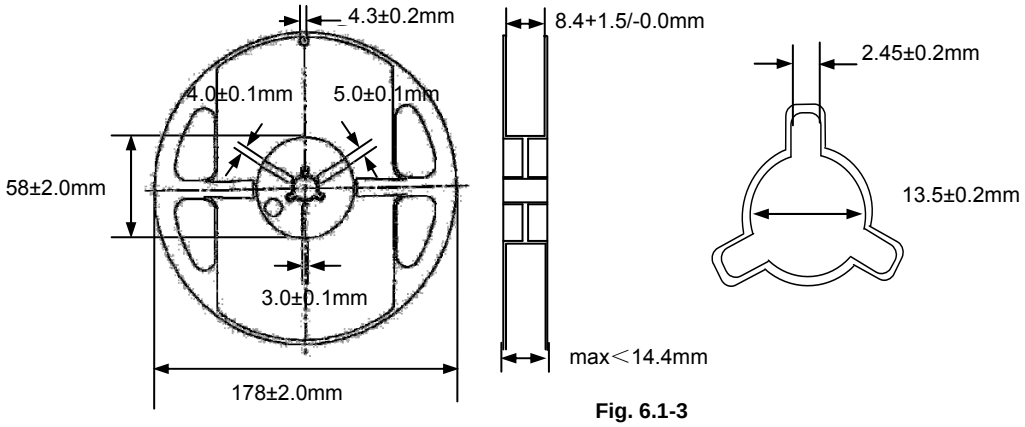


Fig. 6.1-3

6.2 Storage

a. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Package must be stored at 40℃ or less and 70% RH or less.

b. The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust of harmful gas (e.g. HCl, sulfurous gas of H_2S).

c. Packaging material may be deformed if package are stored where they are exposed to heat of direct sunlight.

d. Minimum packages, such as polyvinyl heat-seal packages shall not be opened until they are used. If opened, use the reels as soon as possible.

*e. Solderability of the product s with external dimensions as 0603[0201] specified in **Clause 5.4.6** shall be guaranteed for 6months from the date of delivery on condition that they are stored at the environment specified in **Clause 3**. For those parts, which passed more than 6 months shall be checked solder-ability before use.*

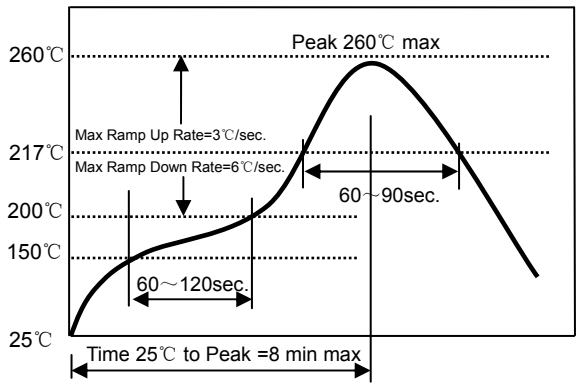
*f. Solderability of the products, except ones with external dimensions as 0603[0201], specified in **Clause 5.4.6** shall be guaranteed for 12 months from the date of delivery on condition that they are stored at the environment specified in **Clause 3**. For those parts, which passed more than 12 months shall be checked solder-ability before use.*

7. Recommended Soldering Technologies

7.1 Re-flowing Profile:

△ Preheat condition: 150 ~200℃/60~120sec.
△ Allowed time above 217℃: 60~90sec.
△ Max temp: 260℃
△ Max time at max temp: 10sec.
△ Solder paste: Sn/3.0Ag/0.5Cu
△ Allowed Reflow time: 2x max

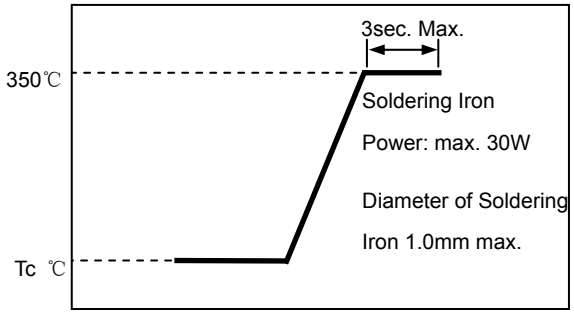
[Note: The reflow profile in the above table is only for qualification and is not meant to specify board assembly profiles. Actual board assembly profiles must be based on the customer's specific board design, solder paste and process, and should not exceed the parameters as the Reflow profile shows.]



7.2 Iron Soldering Profile.

△ Iron soldering power: Max.30W
△ Pre-heating: 150 ℃/60 sec.
△ Soldering Tip temperature: 350℃ Max.
△ Soldering time: 3sec Max.
△ Solder paste: Sn/3.0Ag/0.5Cu
△ Max.1 times for iron soldering

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]



8. Supplier Information

a) Supplier:
Shenzhen Sunlord Electronics Co., Ltd.
b) Manufacturer:
Shenzhen Sunlord Electronics Co., Ltd.
c) Manufacturing Address:
Sunlord Industrial Park, Dafuyuan Industrial Zone, Guanlan, Shenzhen, China
Zip: 518110

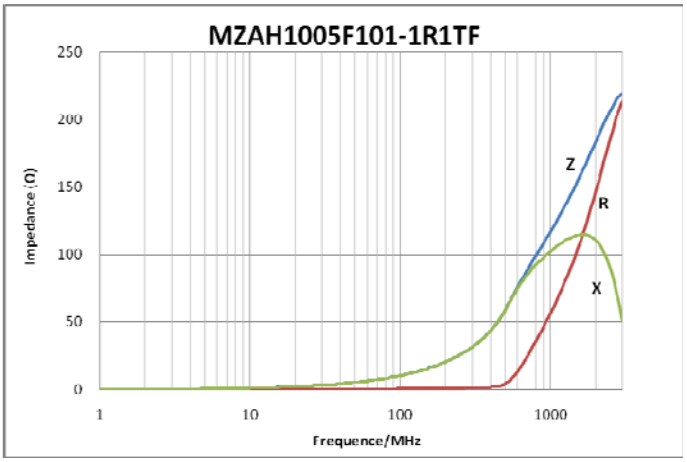
Appendix A: Electrical Characteristics

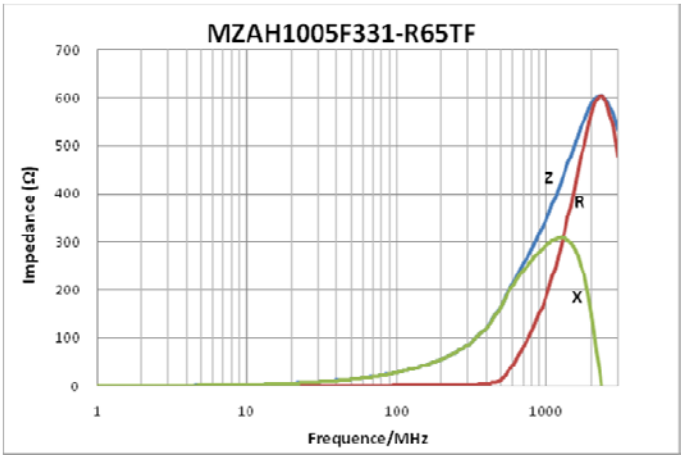
I. MZAH Series

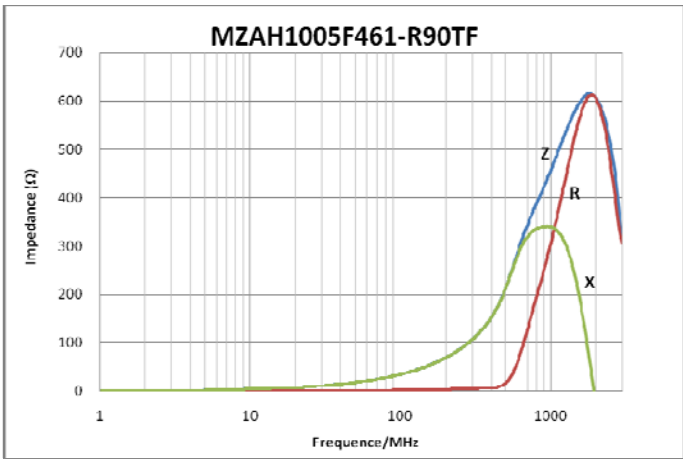
Part Number	Impedance (Ω)			DCR (Ω)	Ir (mA)	Thickness
	Typ.	Min	@1.7GHz(typ.)	Max.	Max.	(mm)[inch]
MZAH1005F101-1R1TF	100 @900MHz	70 @900MHz	160	0.100	1100	0.5±0.15 [0.020±0.006]
MZAH1005F331-R65TF	330 @900MHz	230 @900MHz	540	0.300	650	
MZAH1005F461-R90TF	460 @1000MHz	300 @1000MHz	600	0.170	900	
MZAH1005F771-R50TF	770 @900MHz	530 @900MHz	900	0.5	500	
MZAH1005F152-R40TF	1500 @900MHz	1000 @900MHz	1000	0.600	400	
MZAH1005F262-R35TF	2600 @900MHz	1800 @900MHz	1450	0.800	350	
MZAH1005F352-R27TF	3500 @900MHz	2500 @900MHz	1600	1.350	270	
MZAH1005F462-R27TF	4600 @900MHz	2800 @900MHz	1800	1.650	270	
MZAH1608G471-1R6TF	470 @900MHz	280 @900MHz	270	0.075	1600	0.8±0.15 [.031±.006]

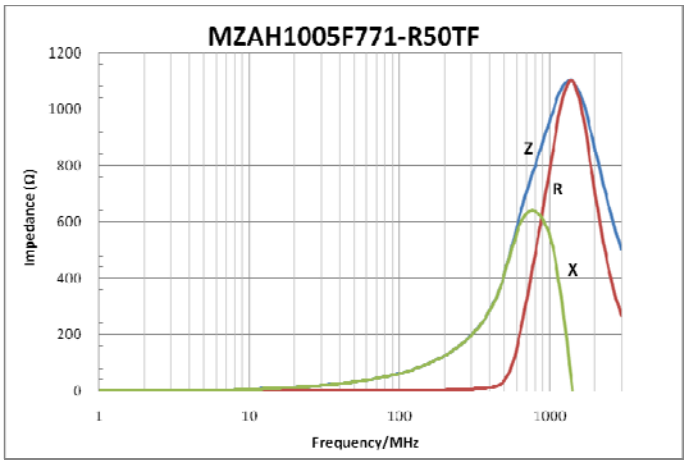
Impedance Frequency Characteristics

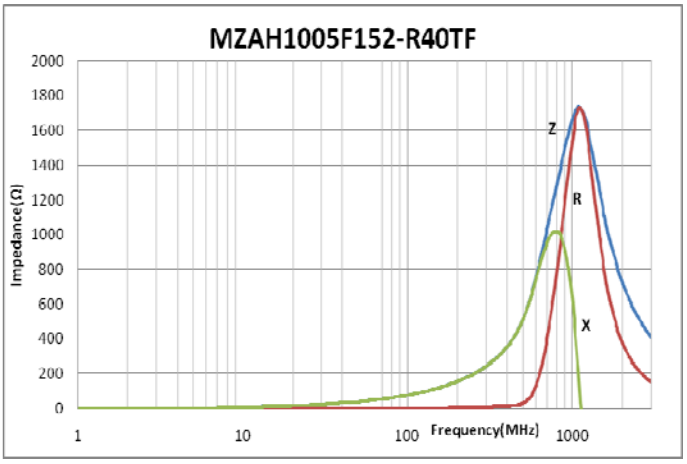
MZAH1005 TYPE

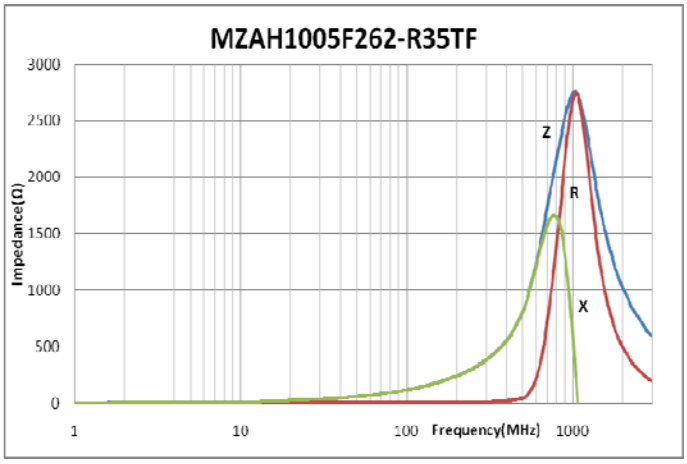


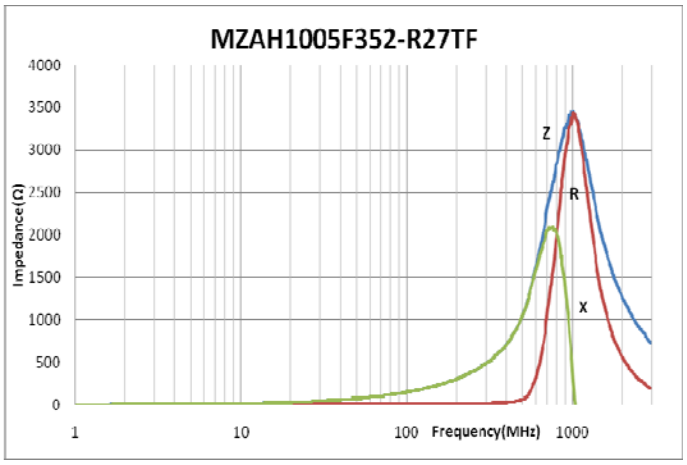


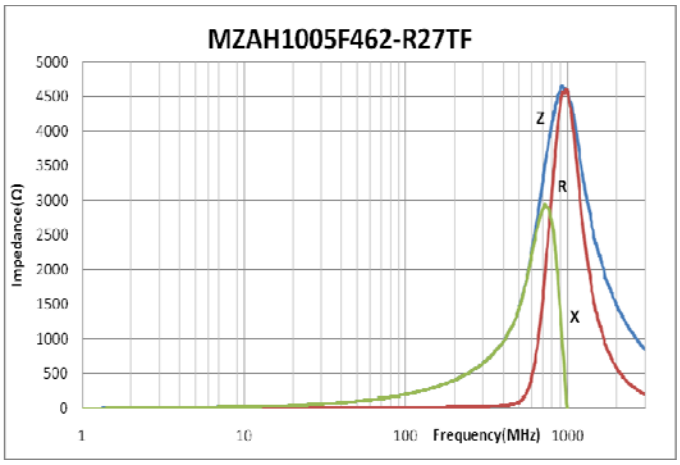












MZAH1608 TYPE